

# Outline

**Welcome & Background**

**Project Overview**

**Break**

**SME ProAM Experiences**

**Wrap-Up**



- ◆ Summary of Accomplishments
- ◆ Post-Project Plans
- ◆ Technology Transfer:
  - Eagle Engineering - Jim Thaxton
  - EPS - Dirk Zwemer
- ◆ Collaboration Opportunities
- ◆ Summary of Benefits

**Discussion - All**

**Overview of Afternoon Sessions**

# Summary of Accomplishments

*Mature  
Prototype  
State*

- ◆ **General techniques:**
  - ◆ Internet-based engineering service bureau (ESB)
  - ◆ X-analysis integration (XAI)
    - ◆ Product data-driven plug-and-play analysis modules
    - ◆ General purpose XAI toolkit

*Early  
Pilot State*

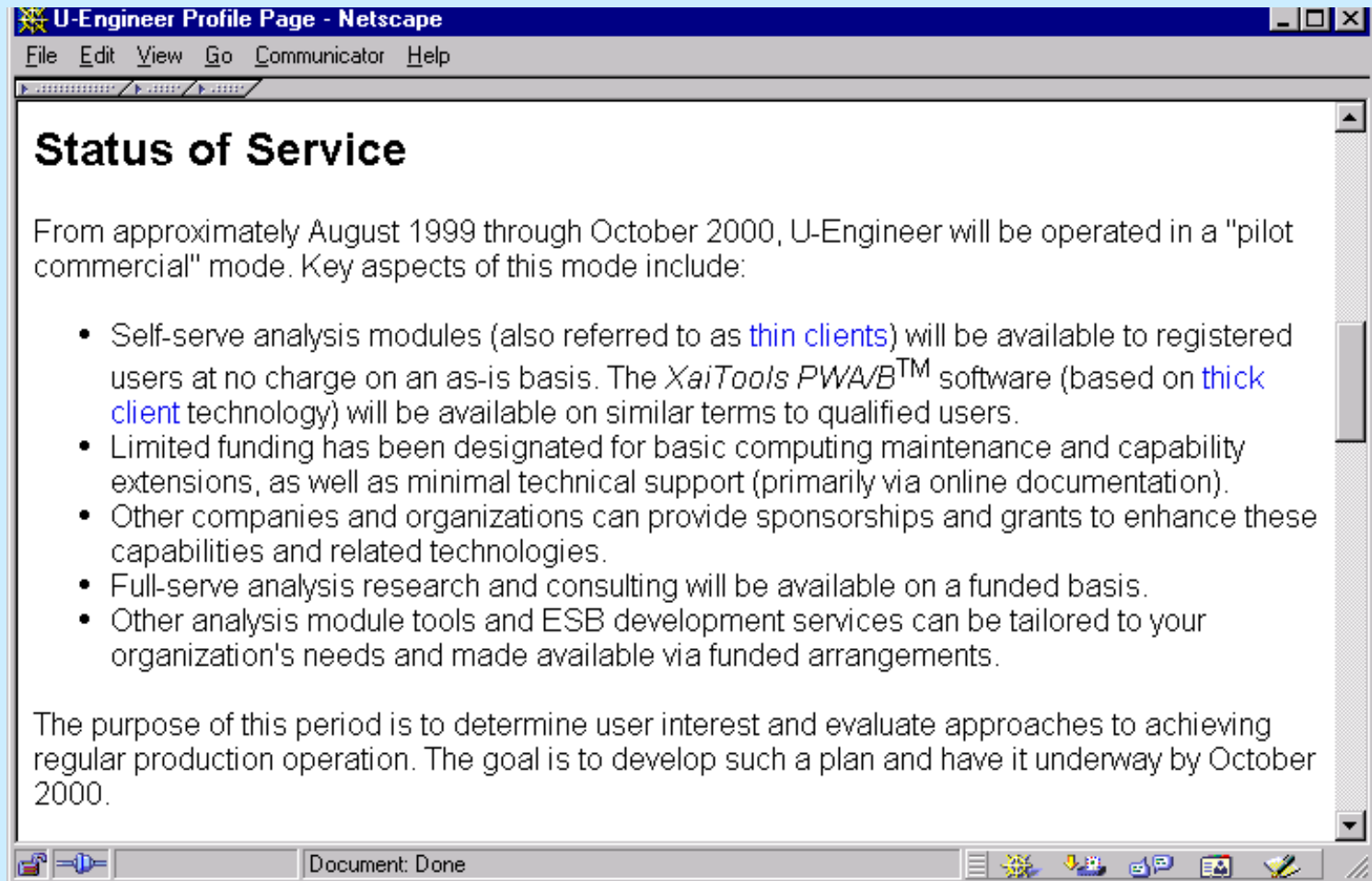
- ◆ **Applications in specific AMCOM context:**
  - ◆ U-Engineer.com pilot commercial ESB with Internet-based PWA/B-specific analysis modules & toolkit
  - ◆ Usage by SMEs in AMCOM supply chain:
    - ◆ Full-serve and self-serve missile examples

# Post-ProAM Plans

Thru 8/99: Limited audience alpha pilot usage

Thru 10/99: Broader audience beta pilot usage

Thru 10/00: General audience pilot usage



The screenshot shows a Netscape browser window titled "U-Engineer Profile Page - Netscape". The address bar is empty. The menu bar includes "File", "Edit", "View", "Go", "Communicator", and "Help". The main content area has a heading "Status of Service" and a paragraph: "From approximately August 1999 through October 2000, U-Engineer will be operated in a 'pilot commercial' mode. Key aspects of this mode include:". Below this is a bulleted list of six items. The status bar at the bottom shows "Document: Done" and several icons.

## Status of Service

From approximately August 1999 through October 2000, U-Engineer will be operated in a "pilot commercial" mode. Key aspects of this mode include:

- Self-serve analysis modules (also referred to as [thin clients](#)) will be available to registered users at no charge on an as-is basis. The *XaiTools PWA/B*<sup>TM</sup> software (based on [thick client](#) technology) will be available on similar terms to qualified users.
- Limited funding has been designated for basic computing maintenance and capability extensions, as well as minimal technical support (primarily via online documentation).
- Other companies and organizations can provide sponsorships and grants to enhance these capabilities and related technologies.
- Full-serve analysis research and consulting will be available on a funded basis.
- Other analysis module tools and ESB development services can be tailored to your organization's needs and made available via funded arrangements.

The purpose of this period is to determine user interest and evaluate approaches to achieving regular production operation. The goal is to develop such a plan and have it underway by October 2000.

# Other Technology Transfer

- ◆ Participation in STEP & GenCAM standards activities
- ◆ Conferences, workshops, etc.
  - DLA Conference (1997)
  - NIST Internet Commerce for Mfg. (ICM) Workshop (1998)
  - UCE-SBA Workshop (1998)
  - ASME Design Engr. Technical Conference (1999)
  - CALS Expo (1999)

# Other Technology Transfer

*(continued)*

- ◆ Engineering service bureau (ESB) concepts:
  - *Eagle Engineering*: Machined parts design-for-mfg. (DFM)
  - *Automata Design, Inc. (ADI)*: PWA/B DFM & electrical test
  - *Electronic Packaging Services, Ltd. Co.(EPS)*: EP analysis
- ◆ Selected proposals:
  - *ATP (EPS, GIT)*: Warpage validation & ESB development
  - *PMTEC (AMCOM, Boeing, CEI, Crane, EPS, GIT)*: Warpage validation & analysis module development
  - *PMTEC (GIT, IPC, NIST, RSI)*: GenCAM/GenX XML development
  - *Prime*: In-house ESB development

# TIGER/ProAM Influence on Eagle Engineering, Inc.

*Presentation by Jim Thaxton*





# Electronic Packaging Services, Ltd. Co.

<http://www.warpfinder.com/>

*Presentation by Dirk Zwemer*

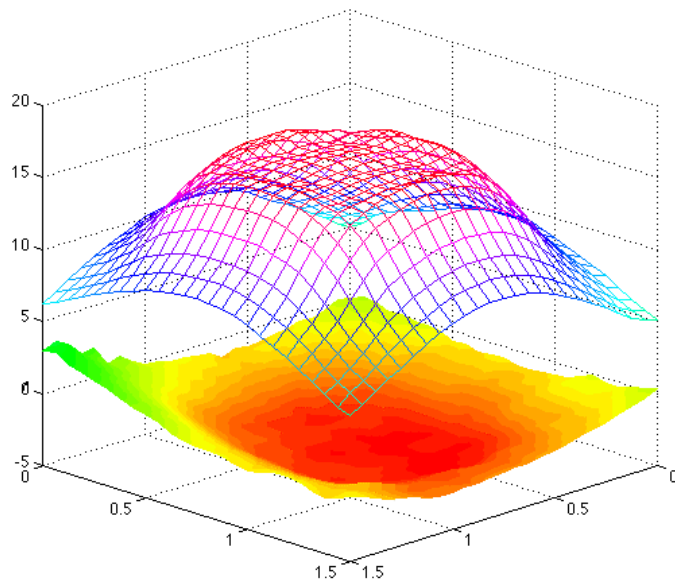
- ◆ Provides Measurement Services and Equipment to Electronic Manufacturers in the area of Thermomechanical Performance and Warpage
- ◆ Four-Year-Old Spin-off of Georgia Tech
- ◆ ~ 1M Annual Sales (85% Commercial)

**3M ASE AMD AlliedSignal Amkor Cabletron Celestica  
Chrysler Compaq Ford Hadco Hewlett-Packard IBM  
ITT Intel LSI Logic Lucent Technologies Motorola NEC  
Raytheon Rockwell Samsung Sematech Siemens Silicon Graphics  
Solectron Sun Microsystems Texas Instruments Toshiba  
Universal Instruments VLSI Technology Viasystems Xilinx**

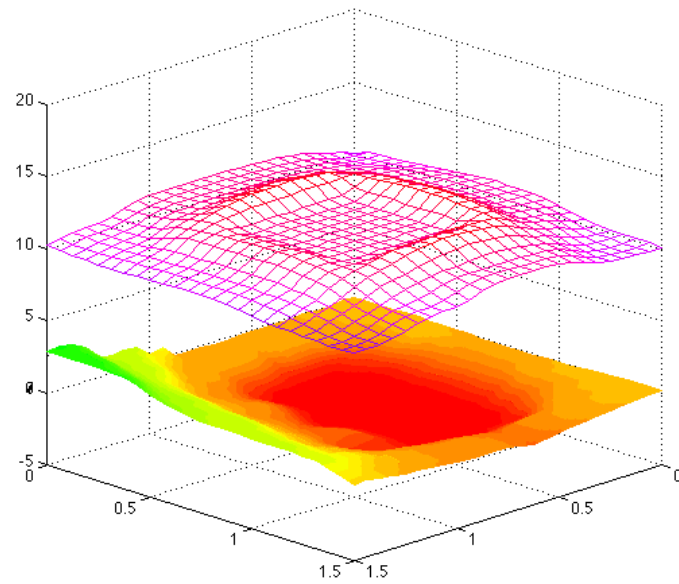
# ELECTRONIC PACKAGING SERVICES, LTD., CO.

## PWB/BGA INTERFACE ANALYSIS

**T = 225 °C at Peak**



**T = 183 °C Cooling**







# EPS ESB Objectives

- ◆ Predictive Warpage Models Deliver Experimental Results in the Most Useful Form
- ◆ **First Step** - EPS Sponsors Engineering Service Bureau (ESB) Web Page on Georgia Tech EIS Lab Server
- ◆ **Further Steps** - EPS works with EIS Lab and Others to Validate Models and Create Materials Properties Databases
- ◆ **Future** - EPS becomes an ESB for Mechanical Performance and Reliability of Electronic Packages

# Collaboration Opportunities

---

- ◆ Company-tailored supply chain pilots
- ◆ Other applications:
  - » Company-specific analysis modules
  - » Intranet/Extranet-based engineering service bureaus
- ◆ Further extensions:
  - » Catalogs with multi-fidelity “drive-before-buy” simulations
  - » Other domains: control systems, propulsion, etc.
- ◆ U-Engineer sponsorship
- ◆ Commercialization of U-Engineer-like ESBs

# Summary of Benefits

- ◆ Internet-based engineering service bureaus (ESBs)
  - ➡ *A key step towards affordable SME analysis*
- ◆ Product data-driven analysis technology
- ◆ Analysis integration toolkit
- ◆ AMCOM missile supply chain application
  - ➡ *U-Engineer & electronic packaging analysis*
- ◆ Exemplar usage of electronic data files like STEP
- ◆ Applicability to other product industries
- ◆ Framework for automated analysis
  - ➡ *Improved product performance, reliability, and manufacturability*